

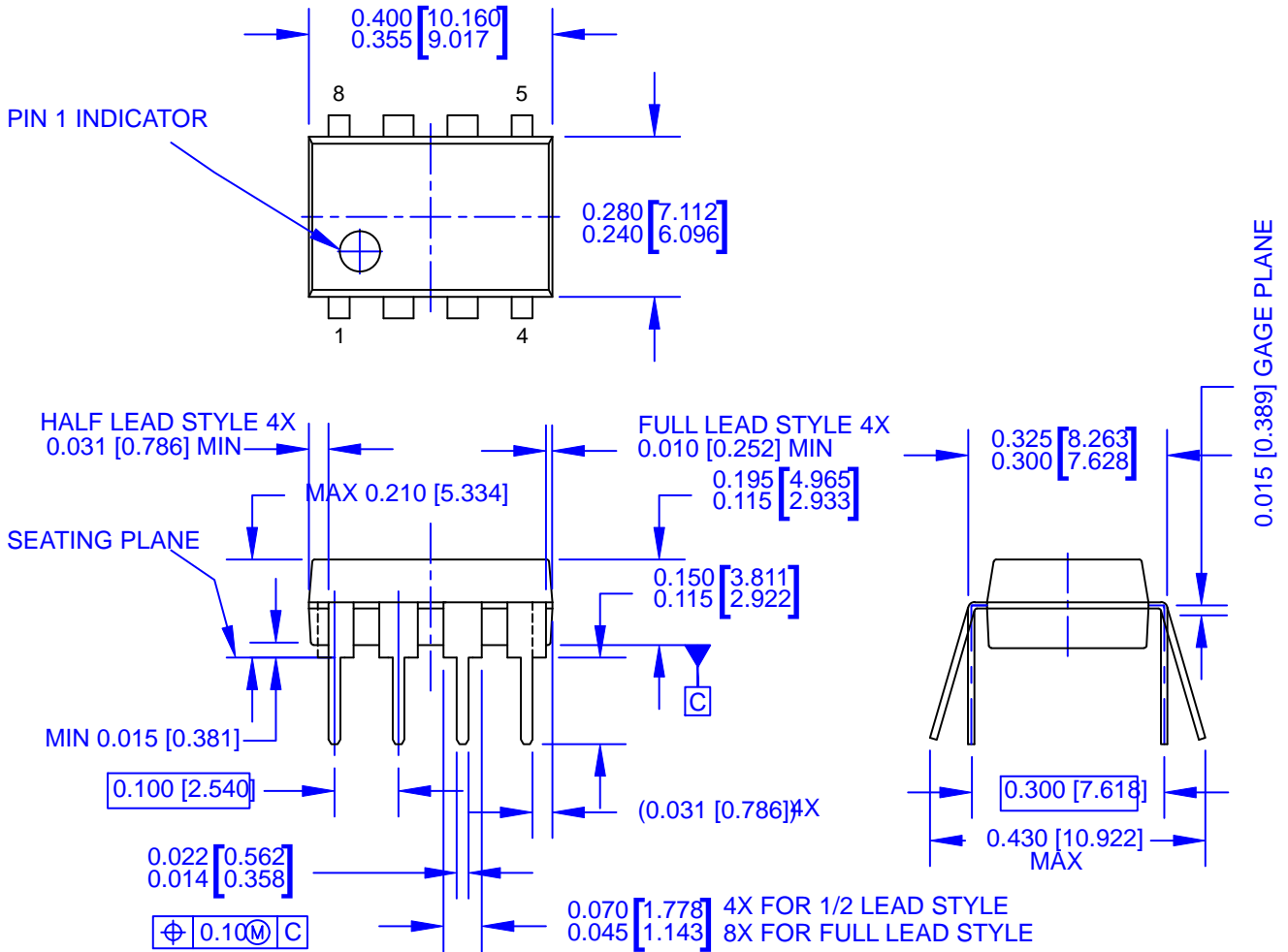
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®



**PDIP8 9.59x6.6, 2.54P**  
CASE 646CN  
ISSUE O

DATE 31 JUL 2016



**NOTES:**

- A) THIS PACKAGE CONFORMS TO JEDEC MS-001 VARIATION BA WHICH DEFINES 2 VERSIONS OF THE PACKAGE TERMINAL STYLE WHICH ARE SHOWN HERE.
- B) CONTROLLING DIMS ARE IN INCHES
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-2009

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>PDIP8 9.59X6.6, 2.54P</b>	<b>PAGE 1 OF 2</b>

